Unit; mm)

# **GP1S23**

### **■** Features

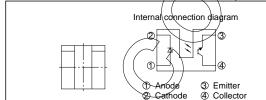
- 1. Ultra-compact
- 2. PWB mounting type package
- 3. High sensing accuracy (Slit width: 0.3mm)
- 4. Gap between light emitter and derector: 2mm

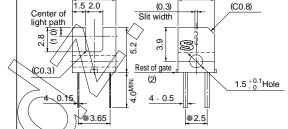
### ■ Applications

- 1. Cameras
- 2. Floppy disk drives

## **Subminiature Photointerrupter**

**■** Outline Dimensions





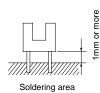
- \* Tolerance:± 0.2mm \* Burr's dimensions : 0.15MAX.
- \* Rest of gate: 0.3MAX.
- \* ( ): Reference dimensions
- \* The dimensions indicated by \* refer to those measured from the lead base.

### ■ Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$ 

2

	Parameter	Symbol	Rating	Unit
Input	Forward current	IF	50	mA
	Reverse voltage	$V_R$	6	V
	Power dissipation	P	75	mW
Output	Collector-emitter voltage	V <sub>CEO</sub>	35	V
	Emitter-collector voltage	V <sub>ECO</sub>	6	V
	Collector current	Ic	20	mA
	Collector power dissipation	Pc	75	mW
	Total power dissipation	P <sub>tot</sub>	100	mW
	Operating temperature	Topr	- 25 to + 85	°C
	Storage temperature	T <sub>stg</sub>	- 40 to + 100	°C
	*1Soldering temperature	$T_{\rm sol}$	260	°C



<sup>\*1</sup> For 3 seconds

### **■** Electro-optical Characteristics

Parameter			Symbol	Conditions	MIN.	TYP.	MAX. Unit
Input	Forward voltage		V <sub>F</sub>	$I_F = 20mA$	-	1.2	1(4 V
	Reverse current		$I_R$	$V_R = 3V$	-	-	10 ptA
Output	Collector dark current		I <sub>CEO</sub>	V <sub>CE</sub> = 20V	-		1 x 10 -7 A
Transfer- charac- teristics	Collector Current		Ic	$I_F = 5mA$ , $V_{CE} = 5V$	40	(-(	400 μ A
	Collector-emitter saturation	n voltage	V <sub>CE(sat)</sub>	$I_F = 10 \text{mA}, I_C = 40 \mu\text{A}$	-	1-/	0,4 / V
	Response time	Rise time	t <sub>r</sub>	$I_C = 0.1$ mA, $V_{CE} = 5$ V, $R_L = 1$ k $\Omega$	- /	50	_150 μs
		Fall time	tf		7/	50	150 µ s

Fig. 1 Forward Current vs. Ambient **Temperature** 

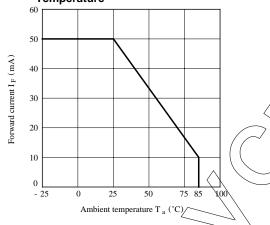


Fig. 3 Forward Current vs. Forward Voltage

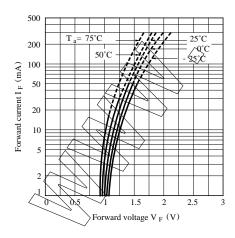


Fig. 2 Power Dissipation vs.

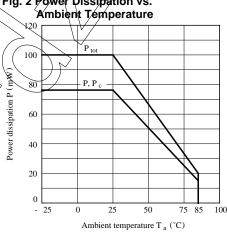


Fig. 4 Collector Current vs. Forward Current

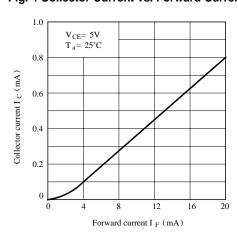


Fig. 5 Collector Current vs.
Collector-emitter voltage

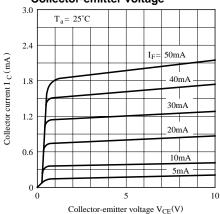


Fig. 7 Collector-emitter Saturation Voltage vs. Ambient Temperature

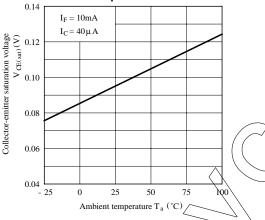


Fig. 9 Response Time vs. Load Resistance

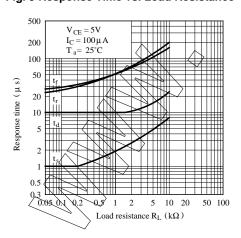


Fig. 6 Collector Current vs.
Ambient Temperature

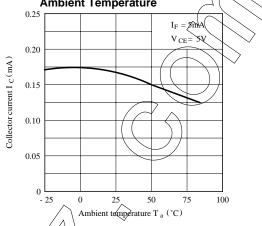
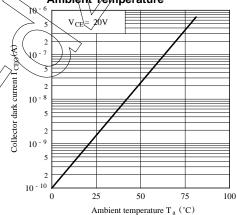
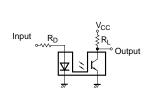


Fig. 8 Collector Dark Current vs.
Ambient Temperature



**Test Circuit for Response Time** 



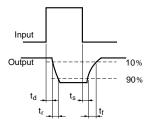
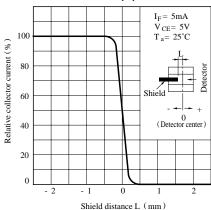


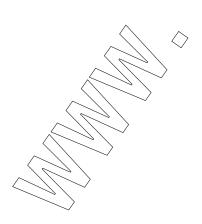
Fig.10 Relative Collector Current vs. Shield Distance (1)



• Please refer to the chapter "Precautions for Use".

Fig.11 Relative Collector Current vs.
Shield Distance (2)

IF = 5 mA
V CE = 5 V
T a= 25 C
Shield Distance L (mm)



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